

Januray 2014

# FQD11P06 / FQU11P06

# P-Channel QFET® MOSFET

-60 V, -9.4 A, 185 mΩ

# **Description**

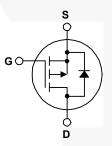
This P-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, • 100% Avalanche Tested DC motor control, and variable switching power applications...

# **Features**

- -9.4 A, -60 V,  $R_{DS(on)}$  = 185 m $\Omega$  (Max.) @  $V_{GS}$  = -10 V,  $I_D = -4.7 A$
- Low Gate Charge (Typ. 13 nC)
- Low Crss (Typ. 45 pF)







# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted.

| Symbol                            | Parameter  |          | FQD11P06TM / FQU11P06TU | Unit |
|-----------------------------------|--|----------|-------------------------|------|
| V <sub>DSS</sub>                  | Drain-Source Voltage   |          | -60                     | V    |
| I <sub>D</sub>                    | Drain Current - Continuous (T <sub>C</sub> = 25°C)   |          | -9.4                    | Α    |
|                                   | - Continuous (T <sub>C</sub> = 100°C)  |          | -5.95                   | Α    |
| I <sub>DM</sub>                   | Drain Current - Pulsed   | (Note 1) | -37.6                   | Α    |
| V <sub>GSS</sub>                  | Gate-Source Voltage  |          | ± 30                    | V    |
| E <sub>AS</sub>                   | Single Pulsed Avalanche Energy   | (Note 2) | 160                     | mJ   |
| I <sub>AR</sub>                   | Avalanche Current  | (Note 1) | -9.4                    | Α    |
| E <sub>AR</sub>                   | Repetitive Avalanche Energy  | (Note 1) | 3.8                     | mJ   |
| dv/dt                             | Peak Diode Recovery dv/dt (Note  |          | -7.0                    | V/ns |
| P <sub>D</sub>                    | P <sub>D</sub> Power Dissipation (T <sub>A</sub> = 25°C) * Power Dissipation (T <sub>C</sub> = 25°C) - Derate above 25°C |          | 2.5                     | W    |
|                                   |  |          | 38                      | W    |
|                                   |  |          | 0.3                     | W/°C |
| T <sub>J</sub> , T <sub>STG</sub> | Operating and Storage Temperature Range  |          | -55 to +150             | °C   |
| T <sub>L</sub>                    | Maximum lead temperature for soldering, 1/8" from case for 5 seconds   | 300      | °C                      |      |

# **Thermal Characteristics**

| Symbol          | Parameter   | FQD11P06TM /<br>FQU11P06TU | Unit |
|-----------------|---|----------------------------|------|
| $R_{\theta JC}$ | Thermal Resistance, Junction to Case, Max. 3.28                                       |                            |      |
| В               | Thermal Resistance, Junction to Ambient (Minimum Pad of 2-oz Copper), Max.            | 110                        | °C/W |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient (*1 in <sup>2</sup> Pad of 2-oz Copper), Max. | 50                         | 1    |

# **Package Marking and Ordering Information**

| Part Number | Top Mark | Package | Packing Method | Reel Size | Tape Width | Quantity   |
|-------------|----------|---------|----------------|-----------|------------|------------|
| FQD11P06TM  | FQD11P06 | D-PAK   | Tape and Reel  | 330 mm    | 16 mm      | 2500 units |
| FQU11P06TU  | FQU11P06 | I-PAK   | Tube           | N/A       | N/A        | 70 units   |

# **Electrical Characteristics**

To = 25°C unless otherwise noted

| Symbol                                  | Parameter   | Test Conditions                                    | Min. | Тур.  | Max.  | Unit |
|---|---|--|------|-------|-------|------|
| Off Cha                                 | aracteristics   |  |      |       |       |      |
| BV <sub>DSS</sub>                       | Drain-Source Breakdown Voltage                        | $V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$     | -60  |       |       | V    |
| ΔBV <sub>DSS</sub><br>/ ΔT <sub>J</sub> | Breakdown Voltage Temperature<br>Coefficient          | $I_D$ = -250 μA, Referenced to 25°C                |      | -0.07 |       | V/°C |
| I <sub>DSS</sub>                        | 7 0 1 1/1 5 : 0 1                                     | $V_{DS} = -60 \text{ V}, V_{GS} = 0 \text{ V}$     |      |       | -1    | μΑ   |
| Ze                                      | Zero Gate Voltage Drain Current                       | V <sub>DS</sub> = -48 V, T <sub>C</sub> = 125°C    |      |       | -10   | μΑ   |
| I <sub>GSSF</sub>                       | Gate-Body Leakage Current, Forward                    | V <sub>GS</sub> = -25 V, V <sub>DS</sub> = 0 V     |      | -     | -100  | nA   |
| $I_{GSSR}$                              | Gate-Body Leakage Current, Reverse                    | V <sub>GS</sub> = 25 V, V <sub>DS</sub> = 0 V      |      | I     | 100   | nA   |
| On Cha                                  | aracteristics   |  |      |       |       |      |
| V <sub>GS(th)</sub>                     | Gate Threshold Voltage                                | $V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$        | -2.0 |       | -4.0  | V    |
| R <sub>DS(on)</sub>                     | Static Drain-Source<br>On-Resistance                  | V <sub>GS</sub> = -10 V, I <sub>D</sub> = -4.7 A   |      | 0.15  | 0.185 | Ω    |
| 9 <sub>FS</sub>                         | Forward Transconductance                              | V <sub>DS</sub> = -30 V, I <sub>D</sub> = -4.7 A   |      | 4.9   |       | S    |
| Dynam                                   | ic Characteristics                                    |  |      |       |       |      |
| C <sub>iss</sub>                        | Input Capacitance                                     | $V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$    |      | 420   | 550   | pF   |
| C <sub>oss</sub>                        | Output Capacitance                                    | f = 1.0 MHz  |      | 195   | 250   | pF   |
| C <sub>rss</sub>                        | Reverse Transfer Capacitance                          |  |      | 45    | 60    | pF   |
| Switchi                                 | ing Characteristics                                   |  |      |       |       |      |
| t <sub>d(on)</sub>                      | Turn-On Delay Time                                    | V <sub>DD</sub> = -30 V, I <sub>D</sub> = -5.7 A,  |      | 6.5   | 25    | ns   |
| t <sub>r</sub>                          | Turn-On Rise Time                                     | $R_{G} = 25 \Omega$                                |      | 40    | 90    | ns   |
| t <sub>d(off)</sub>                     | Turn-Off Delay Time                                   | 11G - 20 sz  |      | 15    | 40    | ns   |
| t <sub>f</sub>                          | Turn-Off Fall Time                                    | (Note 4)   |      | 45    | 100   | ns   |
| Qg                                      | Total Gate Charge                                     | V <sub>DS</sub> = -48 V, I <sub>D</sub> = -11.4 A, |      | 13    | 17    | nC   |
| Q <sub>gs</sub>                         | Gate-Source Charge                                    | V <sub>GS</sub> = -10 V                            | /    | 2.0   |       | nC   |
| Q <sub>gd</sub>                         | Gate-Drain Charge                                     | (Note 4)   |      | 6.3   |       | nC   |
| Drain-S                                 | Source Diode Characteristics a                        | nd Maximum Ratings                                 |      |       |       |      |
| I <sub>S</sub>                          | Maximum Continuous Drain-Source Diode Forward Current |  |      |       | -9.4  | Α    |
| I <sub>SM</sub>                         | Maximum Pulsed Drain-Source Diode Forward Current     |  |      | -     | -37.6 | Α    |
| V <sub>SD</sub>                         | Drain-Source Diode Forward Voltage                    | V <sub>GS</sub> = 0 V, I <sub>S</sub> = -9.4 A     |      | -     | -4.0  | V    |
| t <sub>rr</sub>                         | Reverse Recovery Time                                 | V <sub>GS</sub> = 0 V, I <sub>S</sub> = -11.4 A,   |      | 83    | //    | ns   |
| Q <sub>rr</sub>                         | Reverse Recovery Charge                               | dI <sub>F</sub> / dt = 100 A/μs                    |      | 0.26  | 1     | μС   |

**Notes:** 1. Repetitive rating: pulse-width limited by maximum junction temperature. 2. L = 2.1 mH,  $I_{AS}$  = -9.4 A,  $V_{DD}$  = -25 V,  $R_G$  = 25  $\Omega$ , starting  $T_J$  = 25°C. 3.  $I_{SD}$  ≤ -11.4 A, di/dt ≤ 300 A/ $\mu$ s,  $V_{DD}$  ≤ BV $_{DSS}$ , starting  $T_J$  = 25°C. 4. Essentially independent of operating temperature.

# **Typical Characteristics**

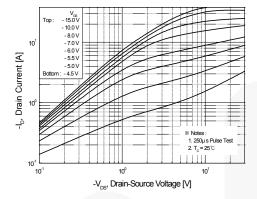


Figure 1. On-Region Characteristics

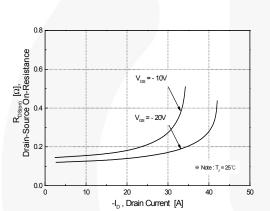


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

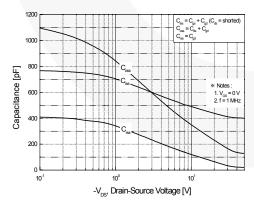


Figure 5. Capacitance Characteristics

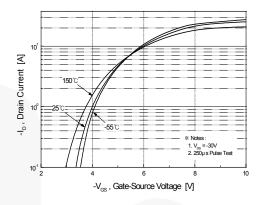


Figure 2. Transfer Characteristics

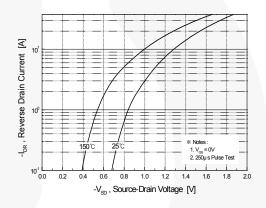


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

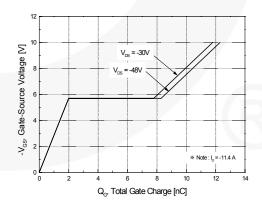


Figure 6. Gate Charge Characteristics

# 12 (Normalized) 1.1 (Normalized) 1.0 (Normalized) 1.1 (No

Typical Characteristics (Continued)

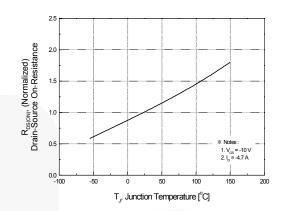
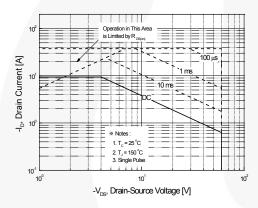


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



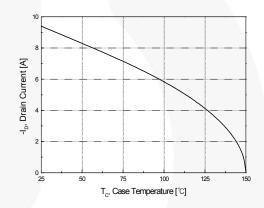


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

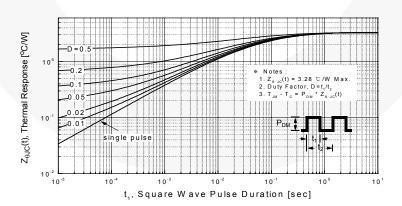


Figure 11. Transient Thermal Response Curve

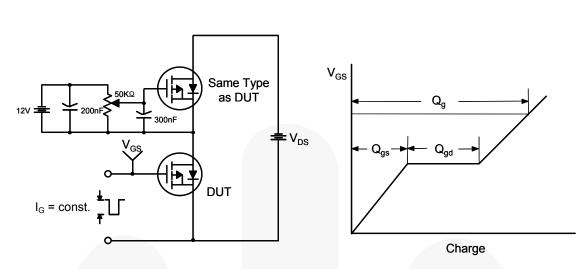


Figure 12. Gate Charge Test Circuit & Waveform

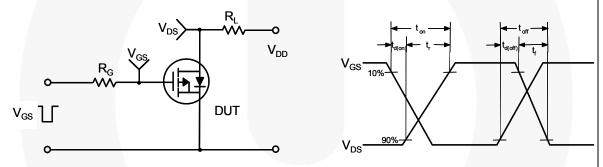


Figure 13. Resistive Switching Test Circuit & Waveforms

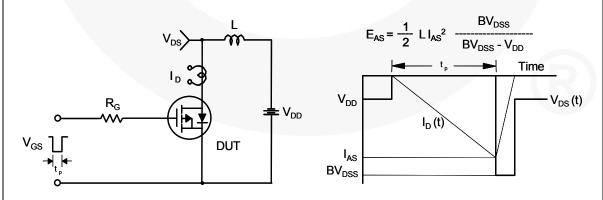
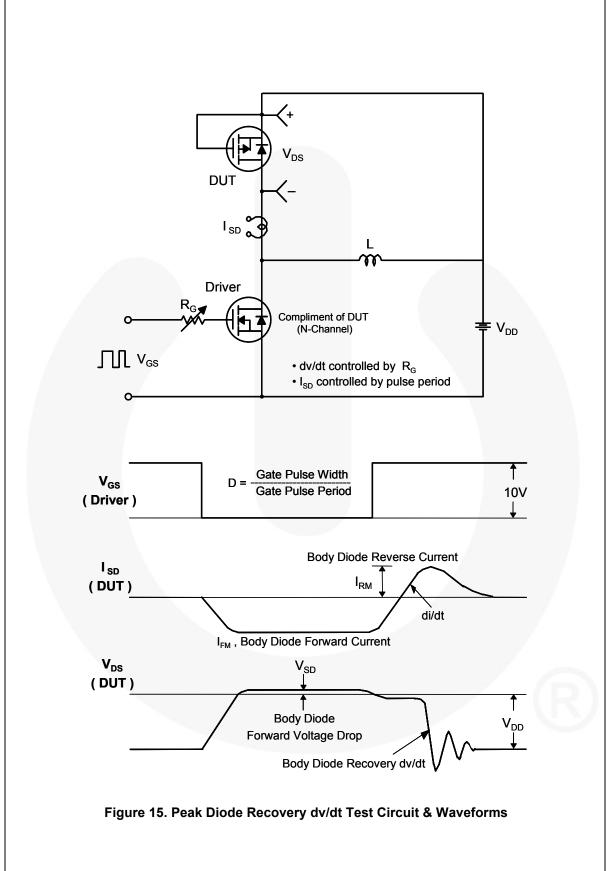


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



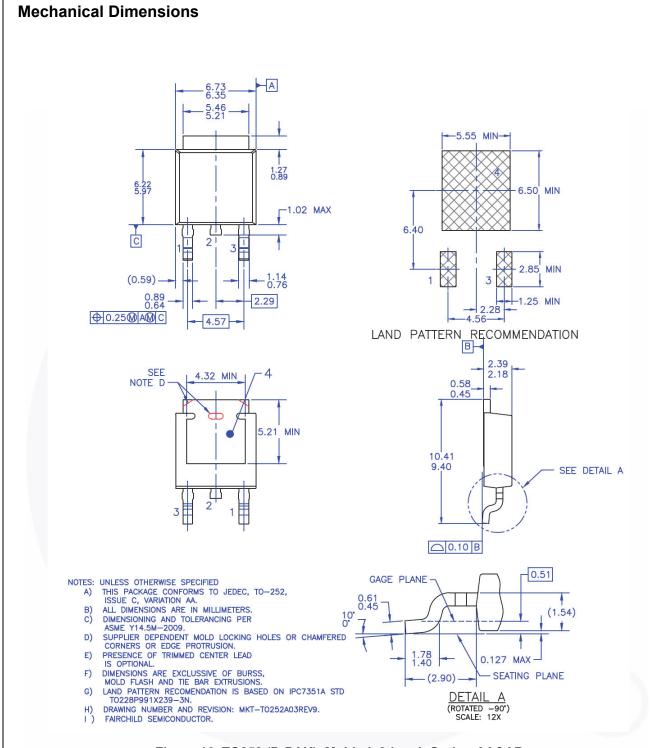


Figure 16. TO252 (D-PAK), Molded, 3-Lead, Option AA&AB

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# **Mechanical Dimensions** C 9.65 8.90 (0.60) -2.29 ◆ 0.25M AM C 3 PLCS NOTES: UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS.

- B) THIS PACKAGE CONFORMS TO JEDEC, TO-251, ISSUE C, VARIATION AA, DATED SEP 1988.
- C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

Figure 17. TO251 (I-PAK), Molded, 3-Lead

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